

GOLD ON ALUMINUM NITRIDE

Thick film gold on aluminum nitride provides excellent wire bond adhesion, electrical conductivity and leach resistance.

Typical Properties of Gold Metallization System		
Resistivity		6.0 mΩ/sq
Printing Resolution	(line/space)	125 μm/125 μm
Wettability	(5 sec dip, 50 In/50 Pb solder)	95 – 100%
Wire Bond Adhesion		
Initial	(Au wire, 4.0 mil dia) @125°C	68 g
Aged 24 h at 300°C	(Au wire, 4.0 mil dia)	58 g
Adhesion*		≥68.9 MPa

*Pull testing with 3.0 mm square pads and epoxy adhesive aluminum studs.

Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products.

Contact us for applications assistance and fast prototyping.

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